

# SOT912-1

plastic thin fine-pitch ball grid array package; 36 balls; body  
3.5 x 3.5 x 0.8 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	TFBGA36
<b>Package type industry code</b>	TFBGA36
<b>Package style descriptive code</b>	TFBGA (thin fine-pitch ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	1-9-2005

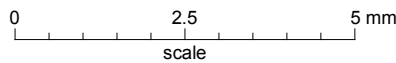
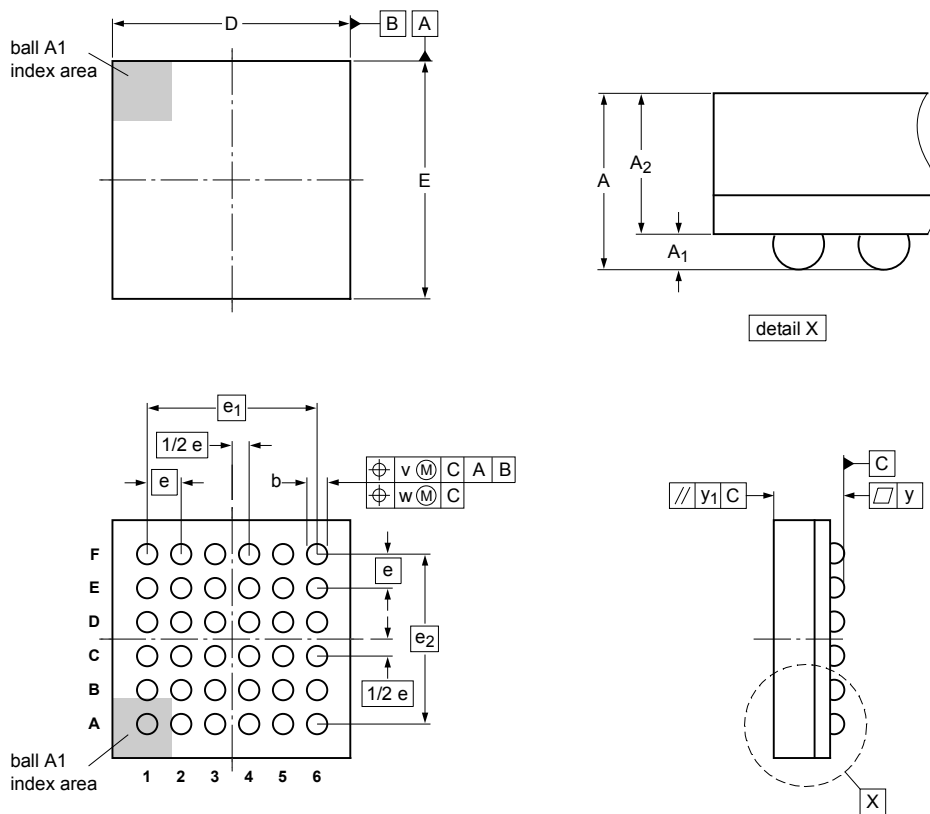
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.4	-	3.5	3.6	mm
E	package width	3.4	-	3.5	3.6	mm
A	seated height	[tbd]	-	1.15	1.15	mm
A <sub>2</sub>	package height	0.75	-	0.8	0.9	mm
n <sub>2</sub>	actual quantity of termination	-	-	36	-	



## 2. Package outline

TFBGA36: plastic thin fine-pitch ball grid array package; 36 balls; body 3.5 x 3.5 x 0.8 mm SOT912-1



DIMENSIONS (mm are the original dimensions)

UNIT	A <sub>max</sub>	A <sub>1</sub>	A <sub>2</sub>	b	D	E	e	e <sub>1</sub>	e <sub>2</sub>	v	w	y	y <sub>1</sub>
mm	1.15	0.25 0.15	0.90 0.75	0.35 0.25	3.6 3.4	3.6 3.4	0.5	2.5	2.5	0.15	0.05	0.08	0.1

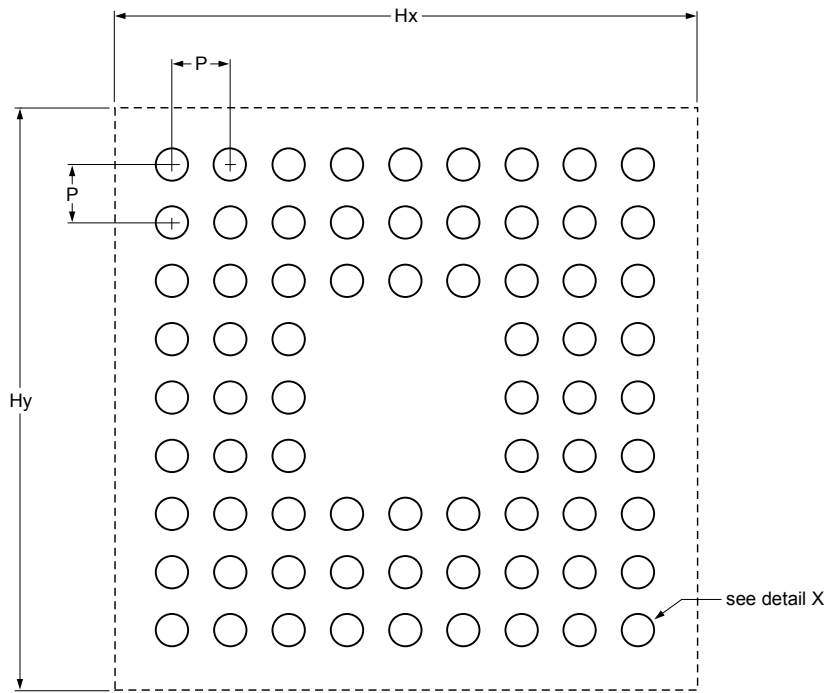
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT912-1	---	---	---			05-08-09 05-09-01

Fig. 1. Package outline TFBGA36 (SOT912-1)




### 3. Soldering

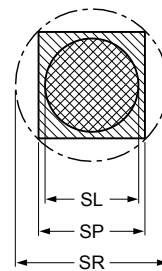
Footprint information for reflow soldering of TFBGA36 package

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Generic footprint pattern  
Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area
- solder resist



detail X

DIMENSIONS in mm

P	SL	SP	SR	Hx	Hy
0.50	0.275	0.300	0.425	3.900	3.900

sot912-1\_fr

Fig. 2. Reflow soldering footprint for TFBGA36 (SOT912-1)

## 4. Legal information

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